

TOSHIBA

Toshiba Memory Corporation Abbreviation Collection

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Abbreviation Collection

* Seal shows our term in the company.

AC	Alternating Current	交流電流
AES	Auger Electron Spectroscopy	オージェ電子分光法
AFM	Atomic Force Microscope	原子間力顕微鏡
AQL	Acceptable Quality Level	合格品質水準
ASIC	Application Specific Integrated Circuit	特定用途向けカスタム集積回路
ATPG	Automatic Test Pattern Generator	テストパターン自動生成
EBテスト	Electron Beam Tester	電子ビームテスト
BEM	Breakdown Energy of Metal	金属配線に大電流を流し溶断するまでのエ ネルギー量で評価する方式
BM	Barrier Metal	バリアメタル
BPSG	Boro Phospho Silicate Glass	硼素リン ケイ酸ガラス
BTI	Bias Temperature Instability	
CAD	Computer Aided Design	コンピュータ支援による設計
CCD	Charge Coupled Device	電荷結合素子
CDM	Charged Device Model	デバイス帯電モデル
CIM	Computer Integrated Manufacturing	コンピュータをベースとした生産管理システム
* CL	Contractual Liability	契約責任
CMOS	Complementary Metal-Oxide Semiconductor	相補性金属酸化膜半導体
CMP	Chemical Mechanical Polishing	化学機械研磨法
CTR	Current Transfer Ratio	電流変換効率
CVD	Chemical Vapor Deposition	化学反応による気相成長
* DAT	Design Approval Test	設計認定試験
DC	Direct Current	直流電流
DIP	Dual Inline Package	リード・ピンが2直列並行に配置されているパ ッケージ
DL	Defect Level	欠陥レベル
DLTS	Deep Level Transient Spectroscopy	不純物準位分光評価
DR	Design Review	設計審査

Abbreviation Collection

ECP	Environmentally Conscious Products	環境調和型製品
EBIC	Electron Beam Induced Current	電子線誘起電流
EEPROM	Electrically Erasable and Programmable Read Only Memory	記憶内容を電氣的に書き換え可能な読み出し専用メモリ
EM	ElectroMigration	エレクトロマイグレーション
EPMA	Electron Probe X-ray Micro Analyzer	X線マイクロアナライザー、電子線マイクロアナライザー
EPROM	Erasable and Programmable Read Only Memory	消去可能な再書き込み可能な読み出し専用メモリ
ESD	ElectroStatic Discharge	静電気放電
ESR	Electron Spin Resonance	電子スピン共鳴
FBGA	Fine pitch Ball Grid Array	BGA(パッケージ)種類の1つ
FIB	Focused Ion Beam	集束イオンビーム
FMEA	Failure Mode and Effects Analysis	故障モード及びその影響度解析
FTA	Fault Tree Analysis	故障の木解析
FT-IR	Fourier Transform Infrared Spectroscopy	フーリエ変換赤外分光
HBM	Human Body Model	人体帯電モデル
HCI	Hot Carrier Injection	ホットキャリア注入
IC	Integrated Circuit	集積回路
IGBT	Insulated Gate Bipolar Transistor	絶縁ゲート型バイポーラトランジスタ
ISS	Ion Scattering Spectroscopy	イオン散乱エネルギー分光
LCC	Leadless Chip Carrier package	リードのない小型、高密度用パッケージ
LED	Light Emitting Diode	発光ダイオード
LEELS	Low Energy Electronic Loss Spectroscopy	低速電子エネルギー損失分光
LSI	Large Scale Integration	大規模集積回路
LQFP	Low profile Quad Flat Package	QFP(パッケージ)種類の1つ
LTPD	Lot Tolerance Percent Defective	Lot 許容不良率

Abbreviation Collection

MM	Machine Model	マシンモデル
MSDS	Material Safety Data Sheet	化学物質安全性データシート
MTBF	Mean Time Between Failures	平均故障間隔時間
MTF	Median Time to Failure	メジアン故障寿命
MTTF	Mean Time To Failure	平均故障寿命
NBTI	Negative Bias Temperature Instability	負バイアス不安定性
OBIC	Optical Beam Induced Current	光励起電流法
OBIRCH	Optical Beam Induced Resistance CHange	光ビーム加熱抵抗変化検出法(オバーク)
ONO	Oxide Nitride Oxide	SiO ₂ /SiN/SiO ₂ (ONO)の3層構造
OSF	Oxidation induced Stacking Fault	酸化誘起積層欠陥
PAT	Production Approval Test	量産品質認定試験
PCB	Printed Circuit Board	プリント回路基板
PDA	Personal Digital Assistant	携帯情報端末
PEM	Photo Emission Microscopy	エミッション顕微鏡
PEP	Photo Etching Process	写真蝕刻工程
PGA	Pin Grid Array package	パッケージの下面からリードピンを取り出すLSIパッケージの1つ
PIXE	Particle Induced X-ray Emission	粒子線励起X線
PL	Product Liability	製造物責任
QAT	Quality Approval Test	量産試作品認定試験
QFP	Quad Flat Package	四方にリードのあるフラットパッケージ
RBS	Rutherford Backscattering Spectrometry	ラザフォード後方散乱
RIE	Reactive Ion Etching	反応性イオンエッチング
SCM	Supply Chain Management	サプライチェーンマネジメント
SEM	Scanning Electron Microscope	走査電子顕微鏡
SILC	Stress Induced Leakage Current	
SIMS	Secondary Ion Mass Spectrometry	二次イオン質量分析装置
SIP	Single In line Package	ピン配列が片側一列だけになっているICパッケージ
SM	Stress Migration	ストレスマイグレーション
SMD	Surface Mounted Devices	面実装デバイス

Abbreviation Collection

SoC	System on Chip	
SPC	Statistical Process Control	統計的品質管理
SPM	Scanning Probe Microscope	走査形プローブ顕微鏡
SSOP	Shrink SOP (Small Outline Package)	SOP(パッケージ)種類の1つ
STM	Scanning Tunneling Microscope	走査形トンネル顕微鏡
TAT	Turn Around Time	納期、応答時間
TCP	Tape Carrier Package	ICチップをテープフィルムと接続し、樹脂を封止するTAB技術を用いたパッケージ
TDDB	Time Dependent Dielectric Breakdown	経時絶縁破壊.酸化膜故障予測手段
TEG	Test Element Group	
TEM	Transmission Electron Microscope	透過電子顕微鏡
TOF-SIMS	Time Of Flight Secondary Ion Mass Spectrometry	飛行時間型2次イオン質量分析装置
TPM	Total Productive Maintenance	全員参加の生産保全
TTF	Time To Failure	
UPS	Ultra-violet Photoelectron Spectroscopy	紫外光励起光電子分光
VPS	Vapor Phase Soldering	蒸気相はんだ付け
XPS	X-ray Photoelectron Spectroscopy	X線光電子分光

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